



Patent

Customer No.: 31561  
Application No.: 10/065,632  
Docket No. 8012-US-PA

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Weng  
Application No. : 10/065,632  
Filed : 2002/11/05  
For : CHIP STRUCTURE WITH BUMPS AND A PROCESS  
FOR FABRICATING THE SAME  
Art Unit : 2814  
Examiner : HA, NATHAN W

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**TRANSMITTAL LETTER**

**002-1-703-872-9306**

**(Via fax: 11 pages, followed by confirmation copy via courier)**

ASSISTANT COMMISSIONER FOR PATENTS  
Arlington, VA22202

Dear Sirs,

In response to the Office Action dated March 18, 2004, please find the relevant paper in response to paper No. 20040304. Following the fax transmission, a hard copy via courier will also be forwarded to the Office.

Enclosed please find:

- ☒ Request for Continued Examination in (2) pages
- ☒ Preliminary Amendment in (7) pages
- ☒ Fax confirmation report
- ☒ Prepaid return postcard

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

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Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: April 14, 2004

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